

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|----------------|------------------|---|-----------------|------------------|-------------------------|-------------------|
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.01281 | 100.0 | 0.26839 |
| | | | Subtotal | 0.01281 | 100 | 0.26839 |
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.24341 | 100.0 | 5.1 |
| | | | Subtotal | 0.24341 | 100 | 5.1 |
| Solder Wire | Tin alloy | Tin (Sn) | 7440-31-5 | 0.02235 | 10.0 | 0.46823 |
| | Silver alloy | Silver (Ag) | 7440-22-4 | 0.00447 | 2.0 | 0.09365 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.19666 | 88.0 | 4.12042 |
| | | | Subtotal | 0.22348 | 100 | 4.6823 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.20085 | 100.0 | 4.20829 |
| | | | Subtotal | 0.20085 | 100 | 4.20829 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.00701 | 0.03 | 0.14694 |
| | Pure metal layer | Zinc (Zn) | 7440-66-6 | 0.00468 | 0.02 | 0.09796 |
| | Pure metal layer | Tin (Sn) | 7440-31-5 | 0.00701 | 0.03 | 0.14694 |
| | Pure metal layer | Iron (Fe) | 7439-89-6 | 0.02571 | 0.11 | 0.53877 |
| | Pure metal layer | Copper (Cu) | 7440-50-8 | 23.33217 | 99.81 | 488.8594 |
| | | | Subtotal | 23.37658 | 100 | 489.79001 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 0.24661 | 100.0 | 5.167 |
| | | | Subtotal | 0.24661 | 100 | 5.167 |
| Mould Compound | Polymer | Tetrabromobisphenol A/Epichlorohydrin polymer | 40039-93-8 | 2.27089 | 3.0 | 47.58 |
| | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 4.54178 | 6.0 | 95.16 |
| | Polymer | Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic) | 29690-82-2 | 7.56963 | 10.0 | 158.6 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.37848 | 0.5 | 7.93 |
| | Filler | Misc. Silica compounds (generic) | 14808-60-7 | 59.04308 | 78.0 | 1237.08 |
| | Flame retardant | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4 | 1309-64-4 | 1.89241 | 2.5 | 39.65 |
| | | | Subtotal | 75.69627 | 100 | 1586 |
| | | | Total | 100.00001 | 100 | 2095.21599 |

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